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Brazing and Soldering of Metals and Alloys

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Message from the Guest Editors

With the development of advanced semiconductor technology, high-power devices and high-density integrated technology have become a popular research focus. The interconnections and bonding within electrical devices are critical for electrical, mechanical and thermal integrity and ultimately impact on the performance and reliability of these devices. This Special Issue focuses on the latest progress in materials, processes and reliability for the metal interconnections. The topics include (but are not limited to) high-power devices, 3D packaging, microsystems, MEMS, and other related fields. The interconnection techniques involved include soldering, brazing, wire-bonding, sometimes sintering, etc. Both experimental and simulation research progress-related articles are welcome for submission to this Special Issue.

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Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

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